



CUSTOM SUBSTRATES

BUILD TO PRINT THIN FILM CERAMIC SOLUTIONS

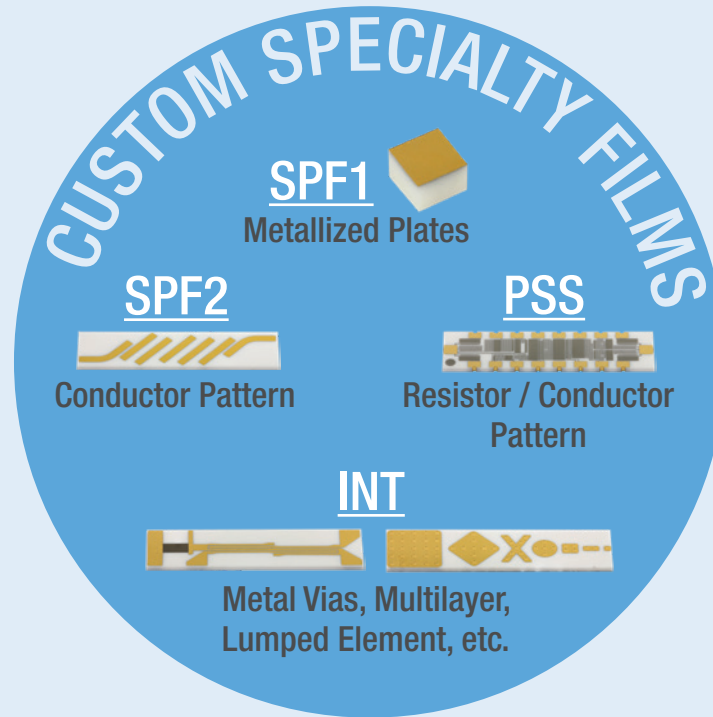
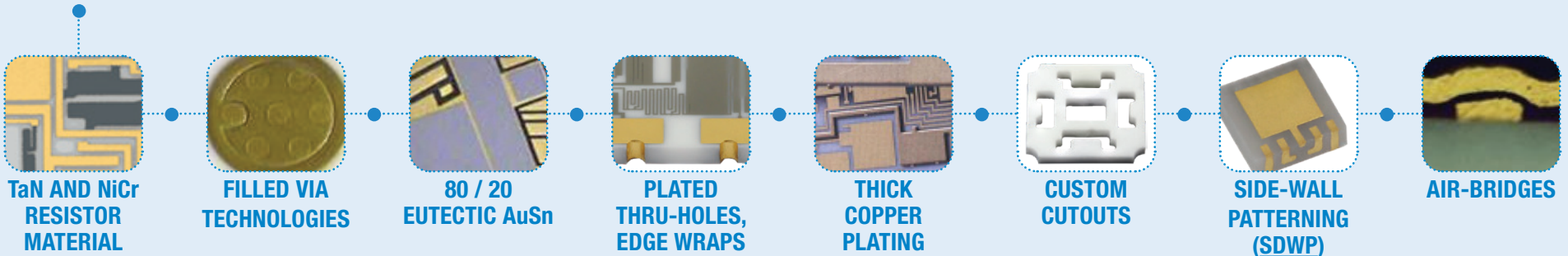
Sputtered Metals:

- Adhesion Layer – Chrome (Cr), Titanium Tungsten (TiW)
- Barrier Layer – Palladium (Pd), Nickel (Ni)
- Conductor Layer – Aluminum (Al), Gold (Au), Copper (Cu)
- Solder Layer - Gold Tin (AuSn)

Plated Metals:

- Barrier Layer – Nickel (Ni)
- Conductor Layer – Gold (Au), Copper (Cu)
- High Current Conductor - Gold (Au), Copper (Cu)

CAPABILITIES



Substrate Materials:

- Alumina (Al_2O_3)
- Aluminum Nitride (AlN)
- Beryllium Oxide (BeO)
- Silicon (Si)
- Quartz (SiO_2)
- Other: Titanates, Ferrites, Sapphire

